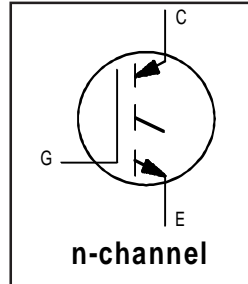


Features

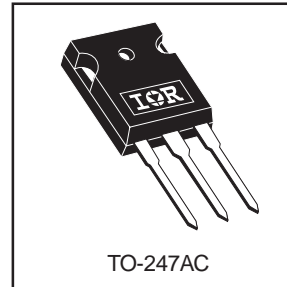
- Standard: Optimized for minimum saturation voltage and low operating frequencies (< 1kHz)
- Generation 4 IGBT design provides tighter parameter distribution and higher efficiency than Generation 3
- Industry standard TO-247AC package



$V_{CES} = 1200V$
$V_{CE(on) \text{ typ.}} = 1.47V$
@ $V_{GE} = 15V, I_C = 33A$

Benefits

- Generation 4 IGBT's offer highest efficiency available
- IGBT's optimized for specified application conditions
- Designed to be a "drop-in" replacement for equivalent industry-standard Generation 3 IR IGBT's



Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	1200	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	57	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	33	
I_{CM}	Pulsed Collector Current ^①	114	
I_{LM}	Clamped Inductive Load Current ^②	114	
V_{GE}	Gate-to-Emitter Voltage	± 20	V
E_{ARV}	Reverse Voltage Avalanche Energy ^③	270	mJ
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	200	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	80	
T_J	Operating Junction and	-55 to +150	°C
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 sec.		
	Mounting torque, 6-32 or M3 screw.	10 lbf•in (1.1N•m)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	0.64	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.24	—	
$R_{\theta JA}$	Junction-to-Ambient, typical socket mount	—	40	
Wt	Weight	6.0 (0.21)	—	g (oz)

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	
V _{(BR)CES}	Collector-to-Emitter Breakdown Voltage	1200	—	—	V	V _{GE} = 0V, I _C = 250μA	
V _{(BR)ECS}	Emitter-to-Collector Breakdown Voltage ④	18	—	—	V	V _{GE} = 0V, I _C = 1.0 A	
ΔV _{(BR)CES} /ΔT _J	Temperature Coeff. of Breakdown Voltage	—	1.22	—	V/°C	V _{GE} = 0V, I _C = 2.0 mA	
V _{CE(ON)}	Collector-to-Emitter Saturation Voltage	—	1.47	1.7	V	I _C = 33A, V _{GE} = 15V	
		—	1.75	—		I _C = 57A	See Fig.2, 5
		—	1.55	—		I _C = 33A, T _J = 150°C	
V _{GE(th)}	Gate Threshold Voltage	3.0	—	6.0		V _{CE} = V _{GE} , I _C = 250μA	
DV _{GE(th)} /DT _J	Temperature Coeff. of Threshold Voltage	—	-11	—	mV/°C	V _{CE} = V _{GE} , I _C = 250μA	
g _{fe}	Forward Transconductance ⑤	27	40	—	S	V _{CE} = 100V, I _C = 33A	
I _{CES}	Zero Gate Voltage Collector Current	—	—	250	μA	V _{GE} = 0V, V _{CE} = 1200V	
		—	—	2.0		V _{GE} = 0V, V _{CE} = 10V, T _J = 25°C	
		—	—	1000		V _{GE} = 0V, V _{CE} = 1200V, T _J = 150°C	
I _{GES}	Gate-to-Emitter Leakage Current	—	—	±100	nA	V _{GE} = ±20V	

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	
Q _g	Total Gate Charge (turn-on)	—	167	251	nC	I _C = 33A	
Q _{ge}	Gate - Emitter Charge (turn-on)	—	25	38		V _{CC} = 400V	See Fig. 8
Q _{gc}	Gate - Collector Charge (turn-on)	—	55	83		V _{GE} = 15V	
t _{d(on)}	Turn-On Delay Time	—	32	—	ns	T _J = 25°C	
t _r	Rise Time	—	29	—		I _C = 33A, V _{CC} = 960V	
t _{d(off)}	Turn-Off Delay Time	—	845	1268		V _{GE} = 15V, R _G = 5.0Ω	
t _f	Fall Time	—	425	638		Energy losses include "tail"	
E _{on}	Turn-On Switching Loss	—	1.80	—	mJ	See Fig. 9, 10, 14	
E _{off}	Turn-Off Switching Loss	—	19.6	—			
E _{ts}	Total Switching Loss	—	21.4	44			
t _{d(on)}	Turn-On Delay Time	—	32	—	ns	T _J = 150°C,	
t _r	Rise Time	—	30	—		I _C = 33A, V _{CC} = 960V	
t _{d(off)}	Turn-Off Delay Time	—	1170	—		V _{GE} = 15V, R _G = 5.0Ω	
t _f	Fall Time	—	1000	—		Energy losses include "tail"	
E _{ts}	Total Switching Loss	—	37	—	mJ	See Fig. 10,11,14	
L _E	Internal Emitter Inductance	—	13	—	nH	Measured 5mm from package	
C _{ies}	Input Capacitance	—	3600	—	pF	V _{GE} = 0V	
C _{oes}	Output Capacitance	—	160	—		V _{CC} = 30V	See Fig. 7
C _{res}	Reverse Transfer Capacitance	—	30	—		f = 1.0MHz	

Notes:

- ① Repetitive rating; V_{GE} = 20V, pulse width limited by max. junction temperature. (See fig. 13b)
- ② V_{CC} = 80%(V_{CES}), V_{GE} = 20V, L = 10μH, R_G = 5.0Ω, (See fig. 13a)
- ③ Repetitive rating; pulse width limited by maximum junction temperature.
- ④ Pulse width ≤ 80μs; duty factor ≤ 0.1%.
- ⑤ Pulse width 5.0μs, single shot.

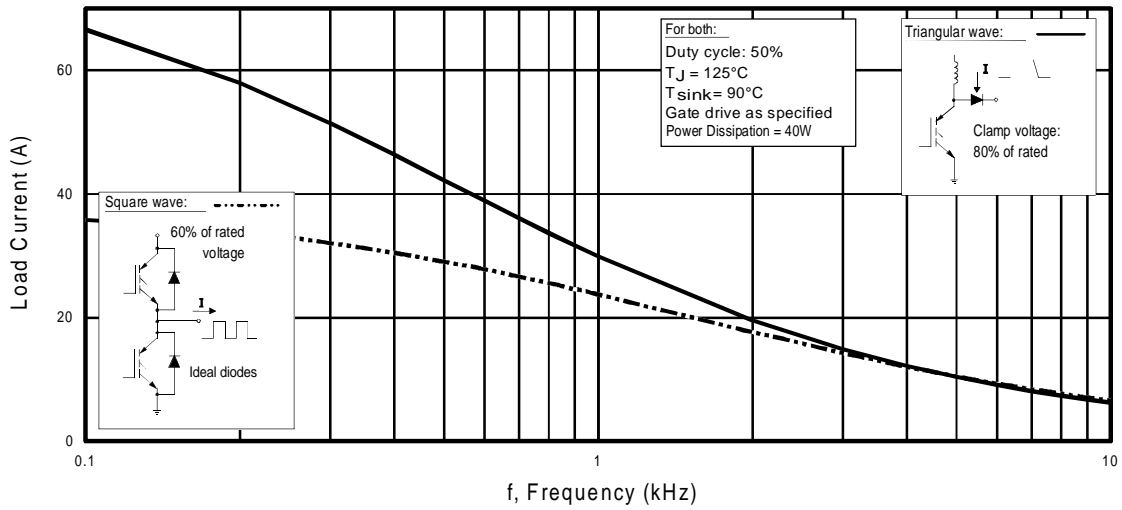


Fig. 1 - Typical Load Current vs. Frequency
(Load Current = I_{RMS} of fundamental)

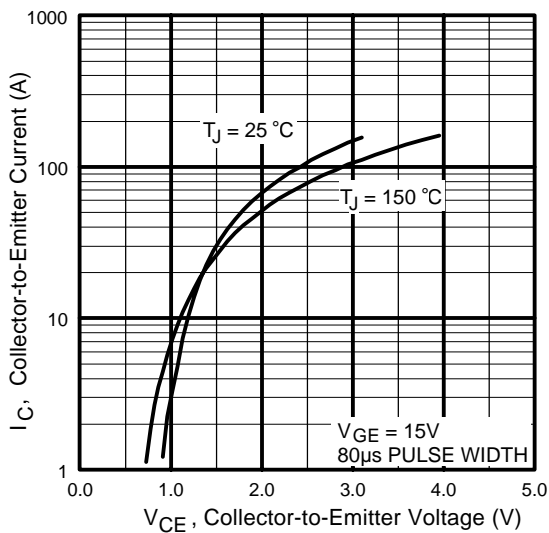


Fig. 2 - Typical Output Characteristics

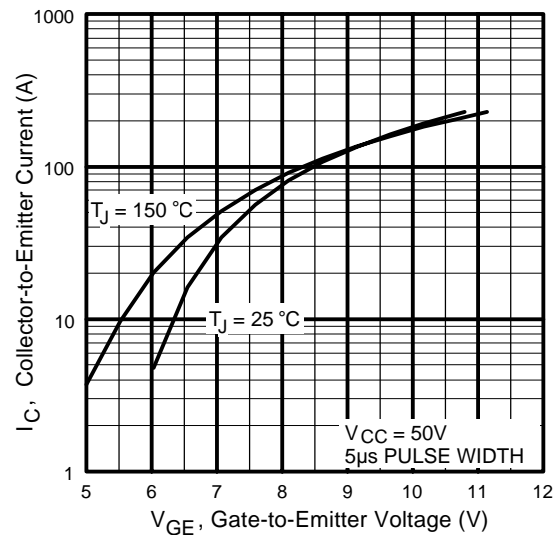


Fig. 3 - Typical Transfer Characteristics

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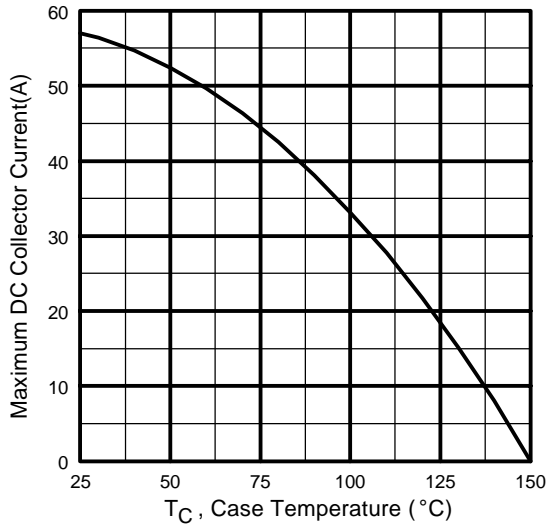


Fig. 4 - Maximum Collector Current vs. Case Temperature

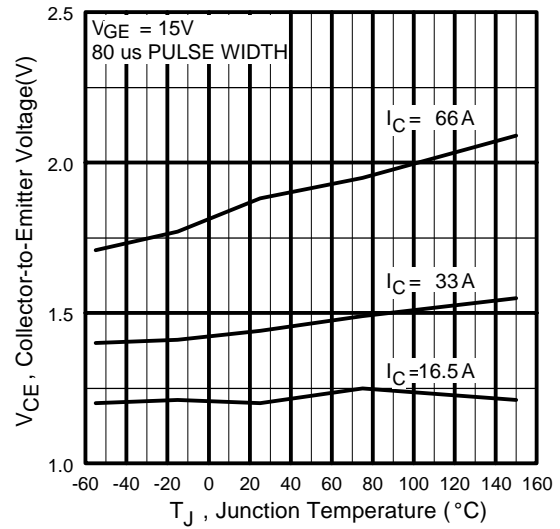


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

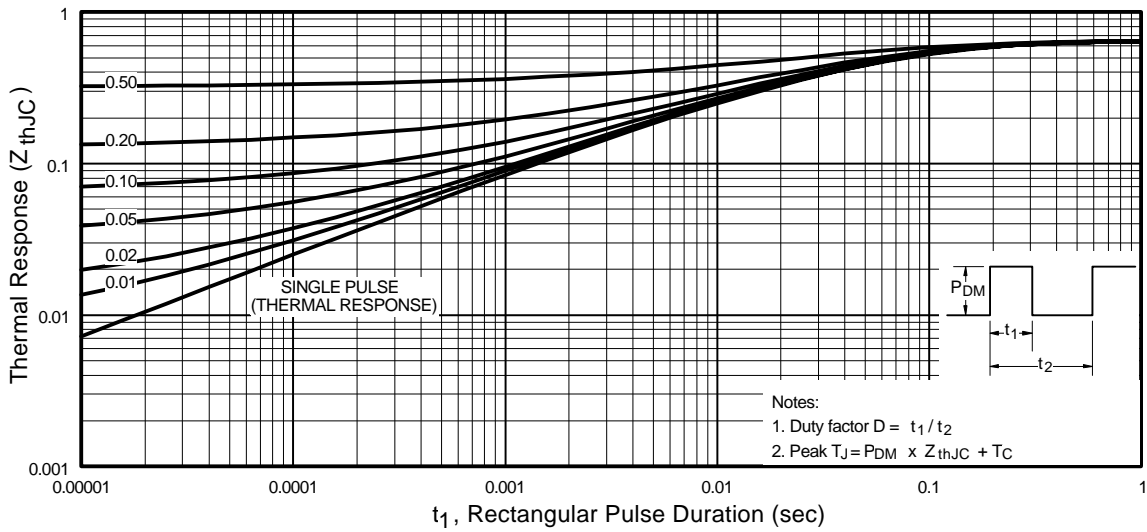


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

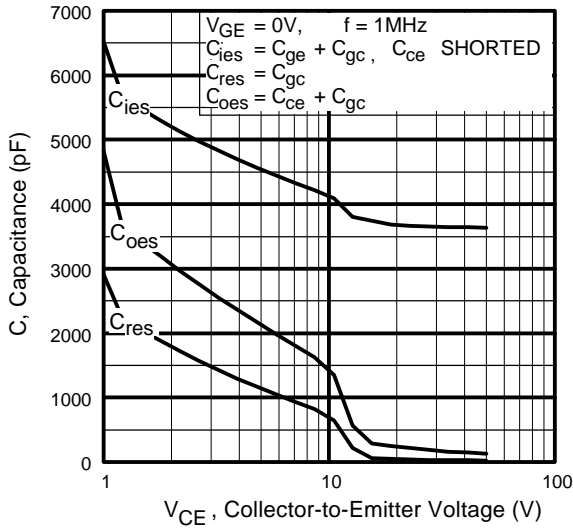


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

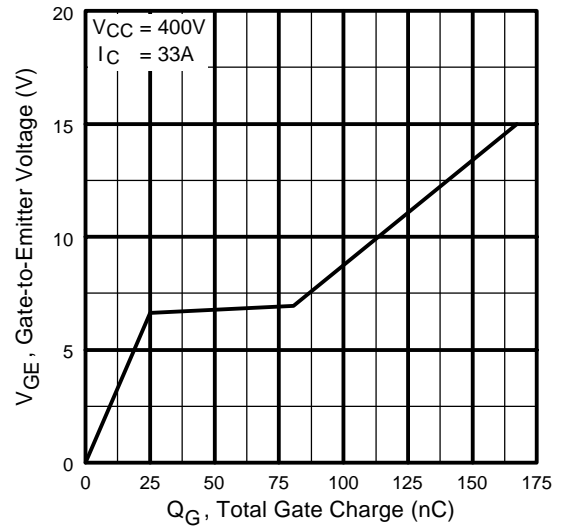


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

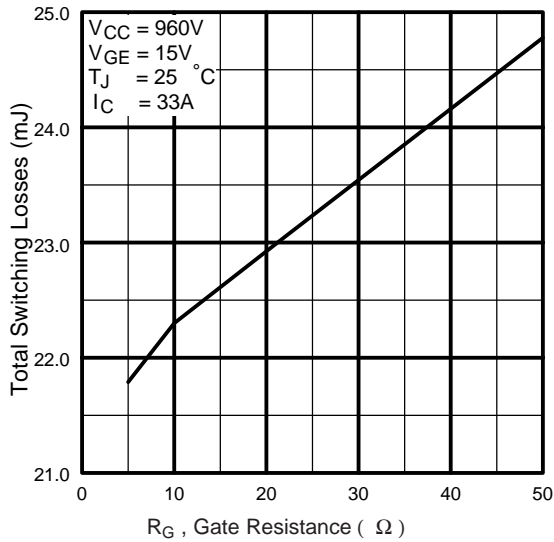


Fig. 9 - Typical Switching Losses vs. Gate Resistance

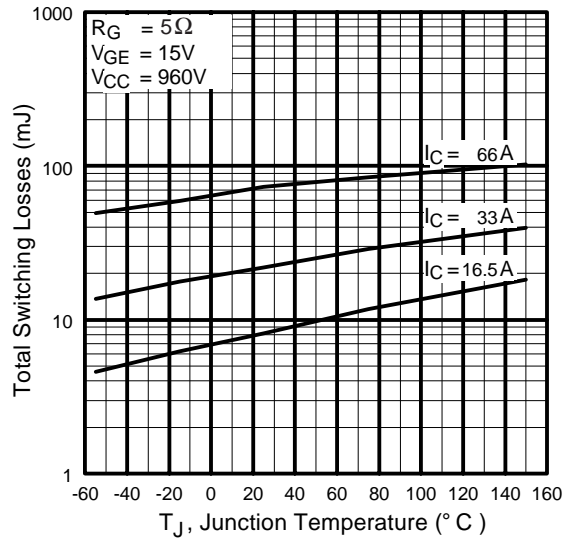


Fig. 10 - Typical Switching Losses vs. Junction Temperature

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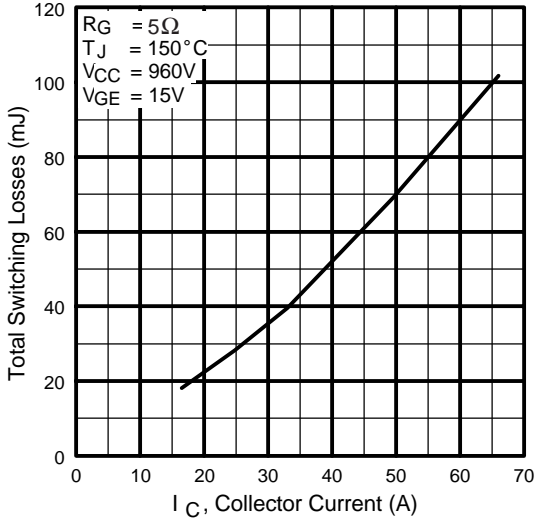


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

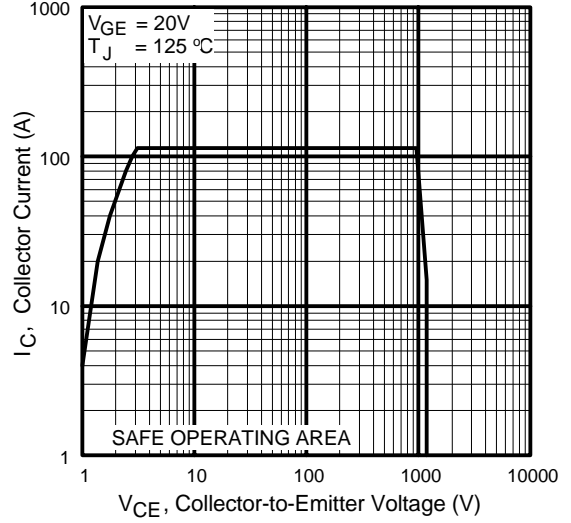
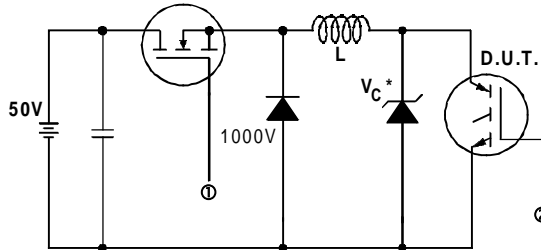


Fig. 12 - Reverse Bias SOA



* Driver same type as D.U.T.; $V_c = 80\%$ of $V_{ce(max)}$
 * Note: Due to the 50V power supply, pulse width and inductor will increase to obtain rated I_d .

Fig. 13a - Clamped Inductive Load Test Circuit

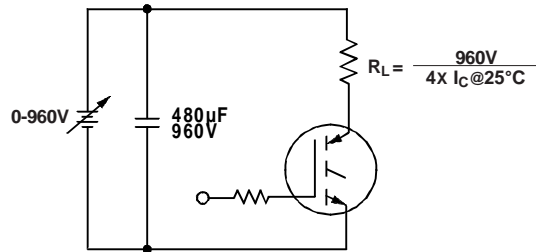


Fig. 13b - Pulsed Collector Current Test Circuit

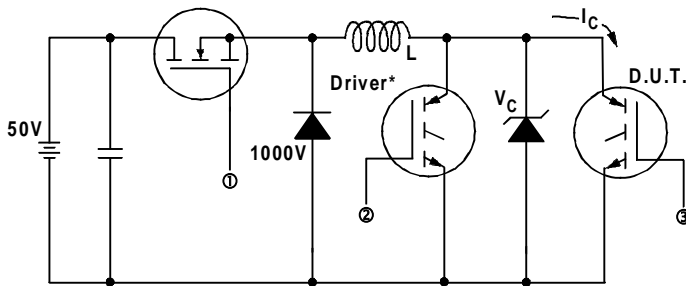


Fig. 14a - Switching Loss Test Circuit

* Driver same type as D.U.T., $V_c = \text{---}V$

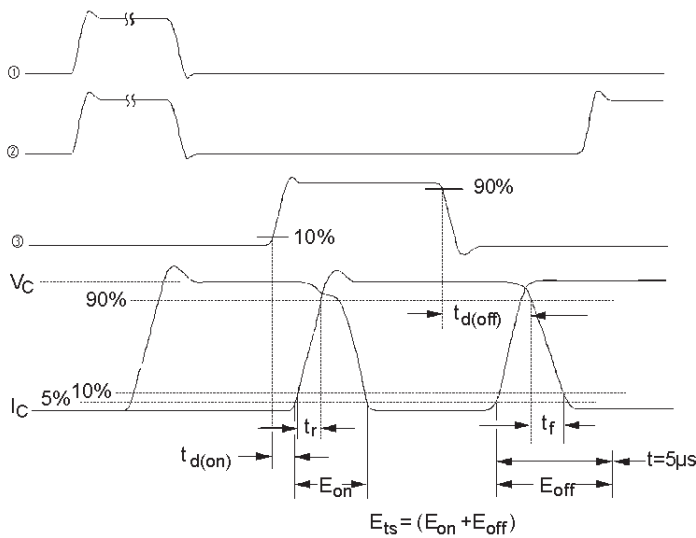


Fig. 14b - Switching Loss Waveforms

Case Outline and Dimensions — TO-247AC

